



Attorney's docket No. 14771, file No. 4-11

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Ohtani Art Unit : 1765
Serial No.: 09/596,755 Examiner : Robert Kunemund
Filed : June 15, 2000
Title : MANUFACTURING METHOD OF SEMICONDUCTOR AND MANUFACTURING
 METHOD OF SEMICONDUCTOR DEVICE

BOX RCE

Commissioner for Patents
Washington, D.C. 20231

February 4, 2002
[Note: February 2, 2002
was a Saturday]

AMENDMENT

Sir:

Please amend the above-identified application as follows.

In the Claims:

Please amend claims 2, 20, 29, and 36 as follows.

2. ^{twice} (Amended) A method for manufacturing a semiconductor device comprising steps of:

forming a semiconductor film over a substrate; and

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CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231

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